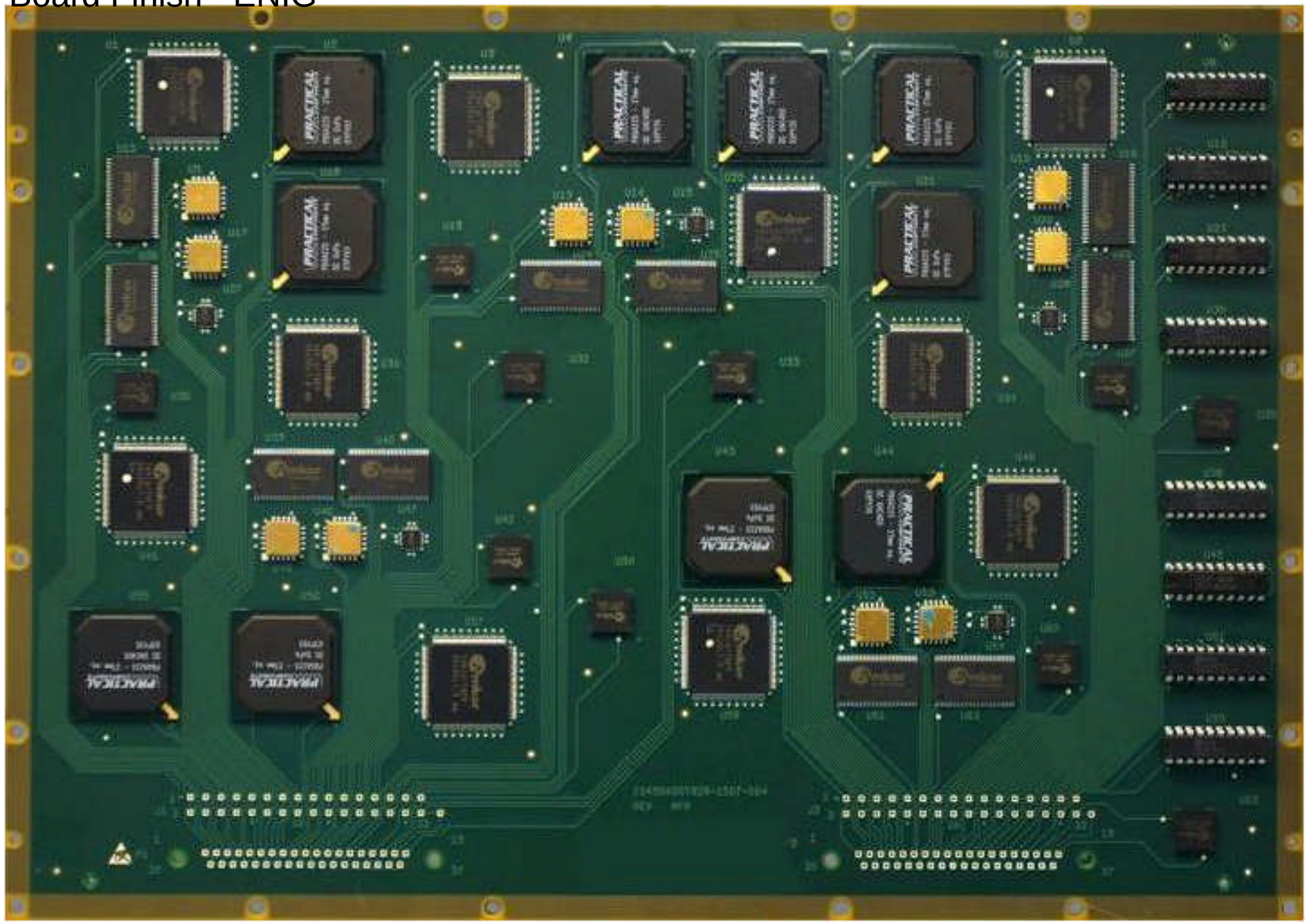
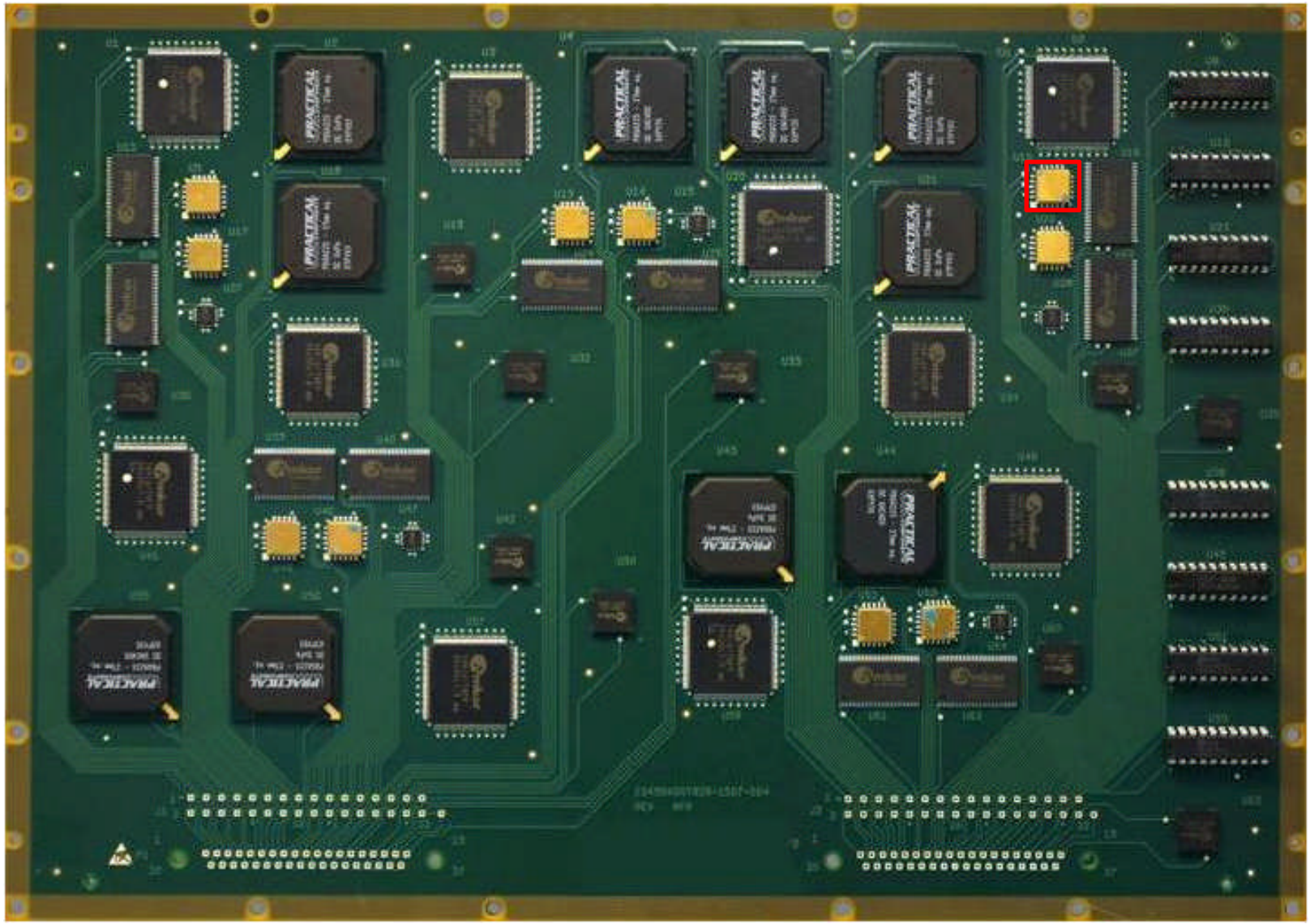
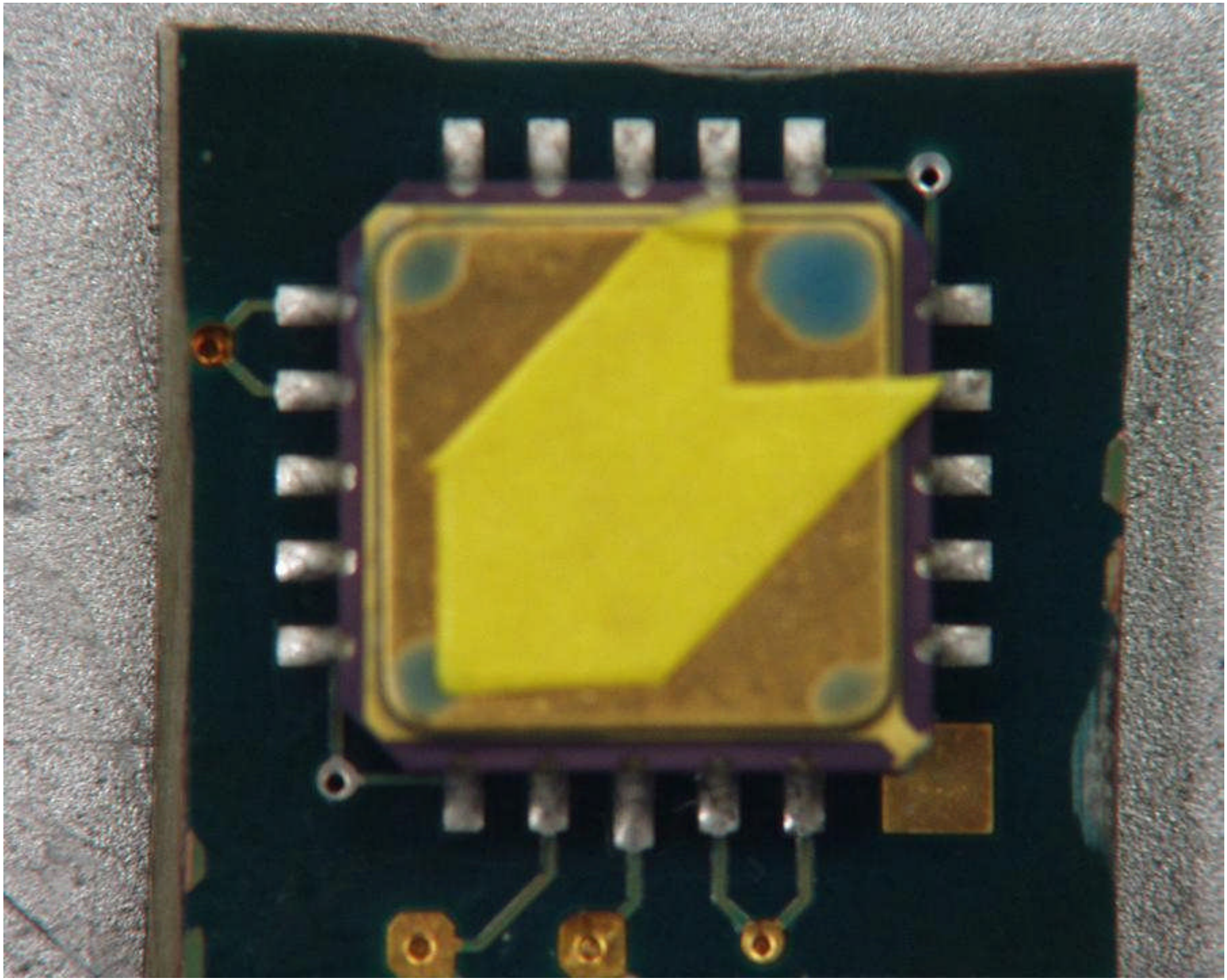
SN93 - Lead-Free Manufactured; Thermal Cycle and Combined Environments Test Vehicle

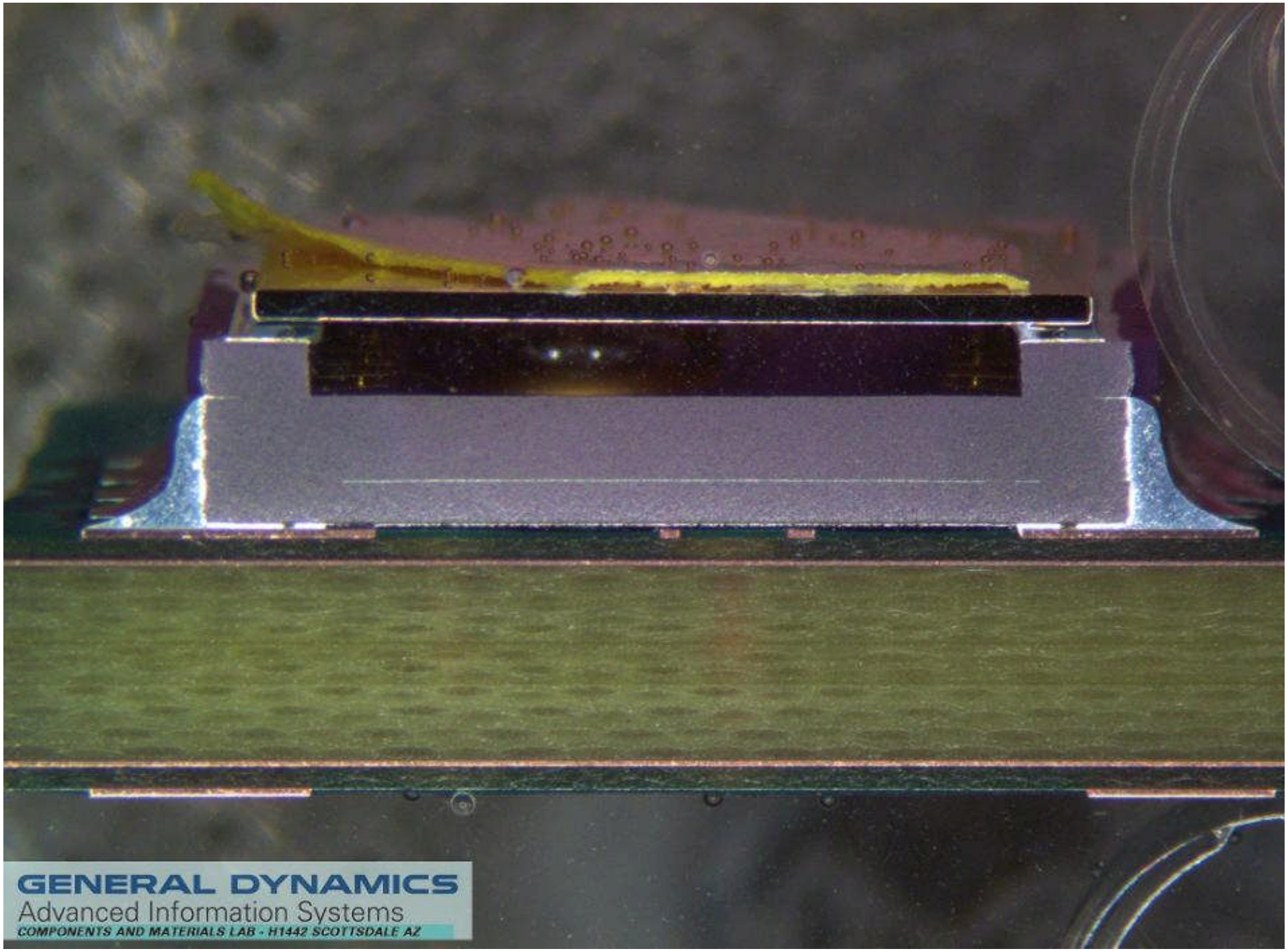
- Assembly Profile – Lead-Free
- Reflow Solder – SAC305
- Wave Solder – SN100C
- Board Finish - ENIG

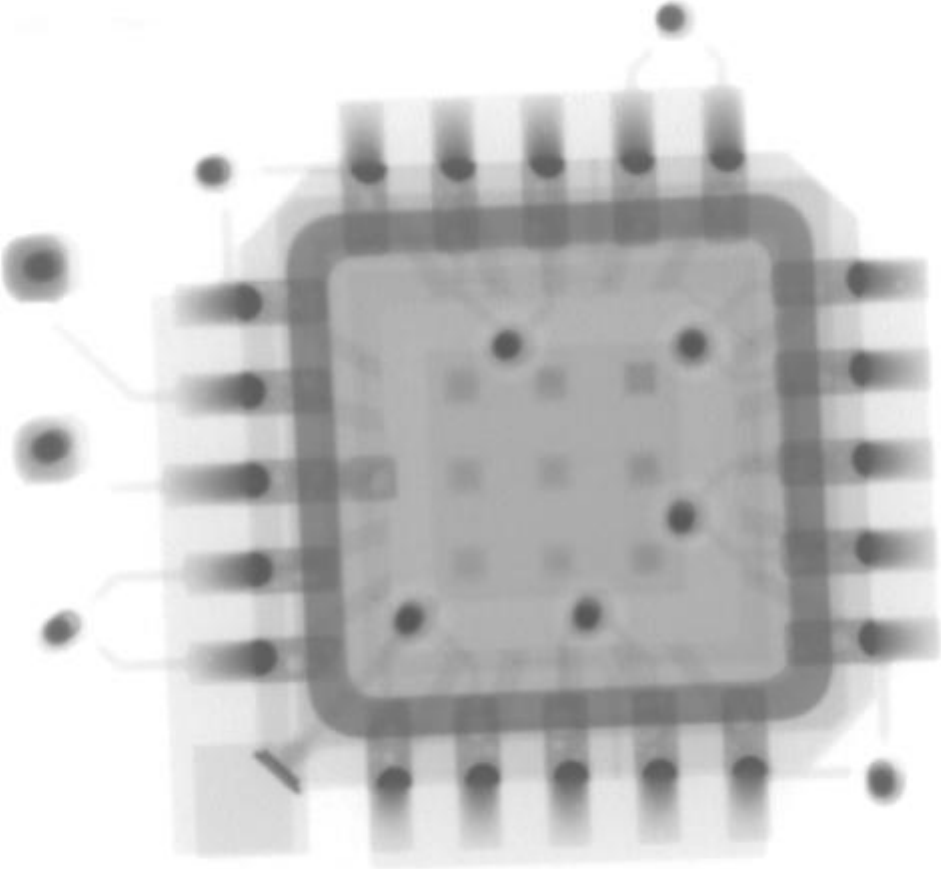


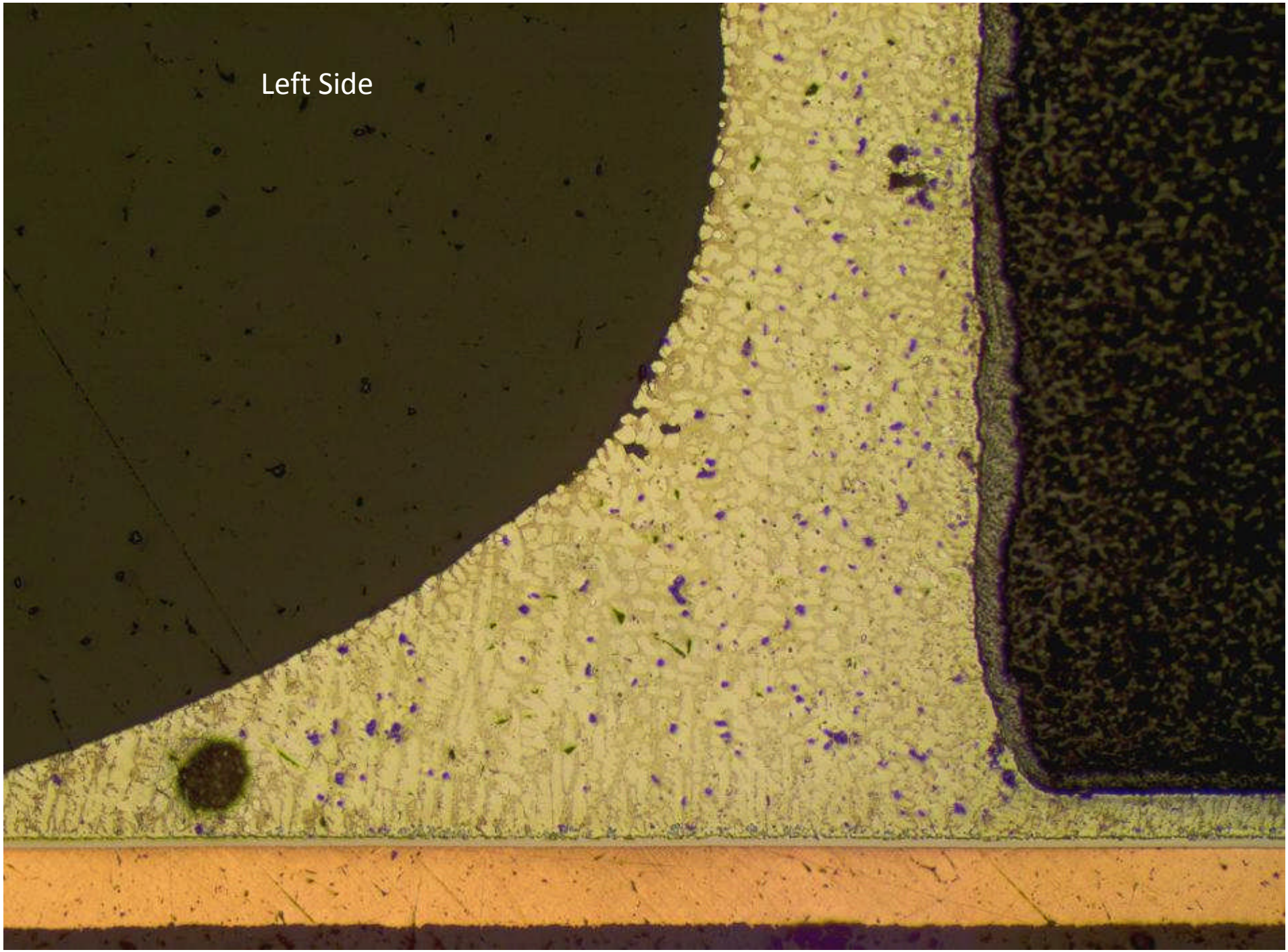
U10 – CLCC-20
SAC305 Finish

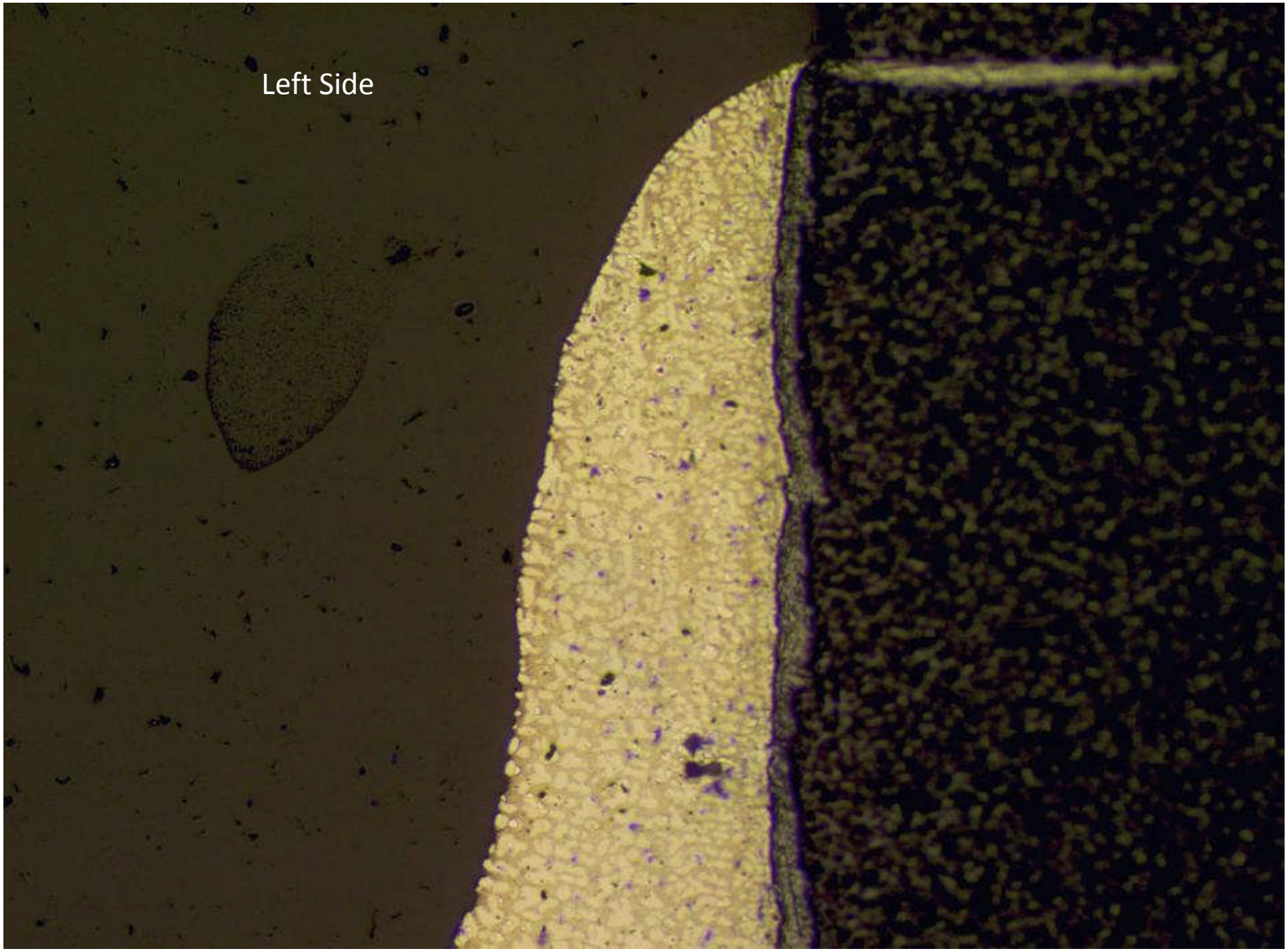




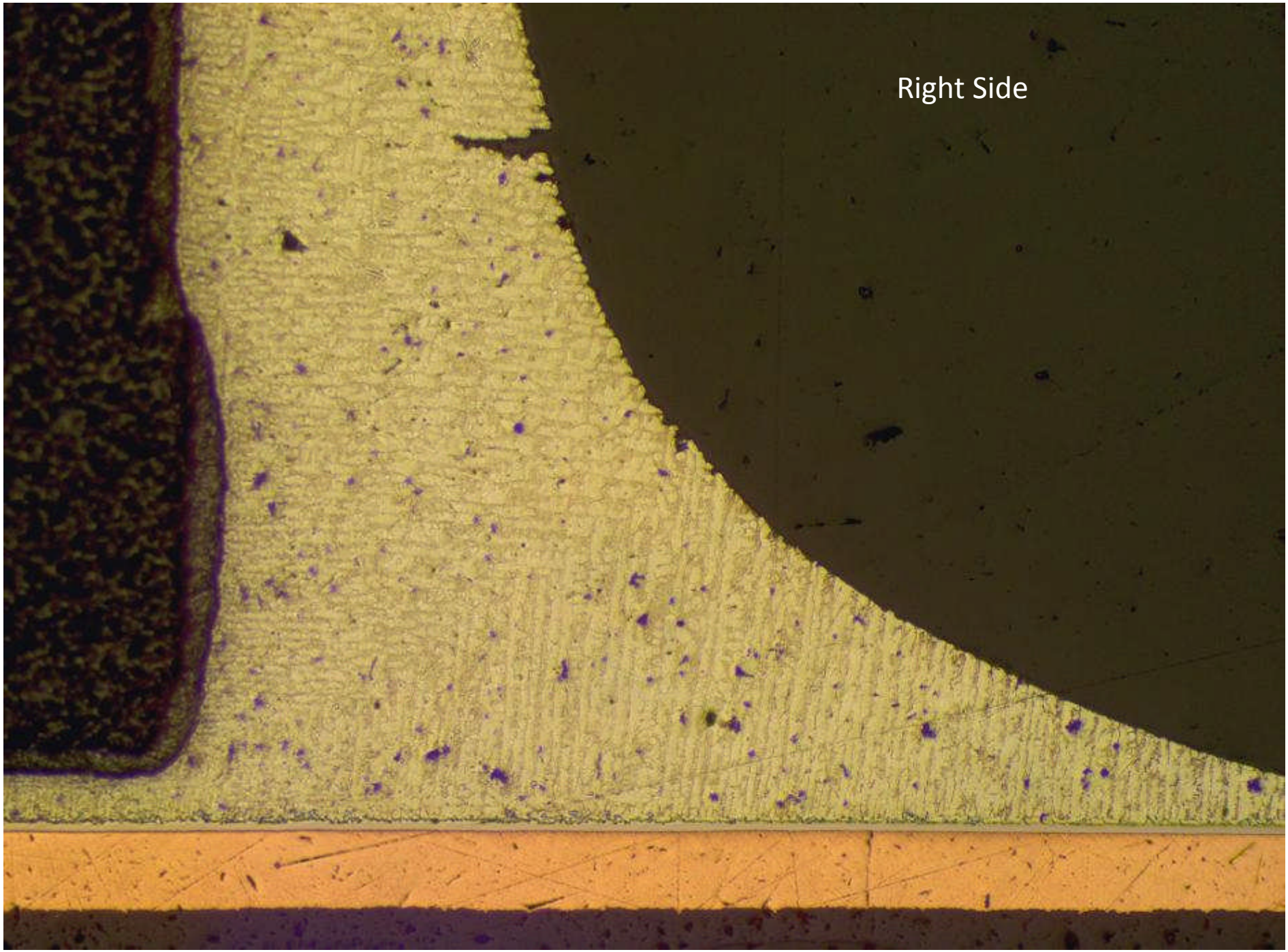

GENERAL DYNAMICS
Advanced Information Systems
COMPONENTS AND MATERIALS LAB - H1442 SCOTTSDALE AZ

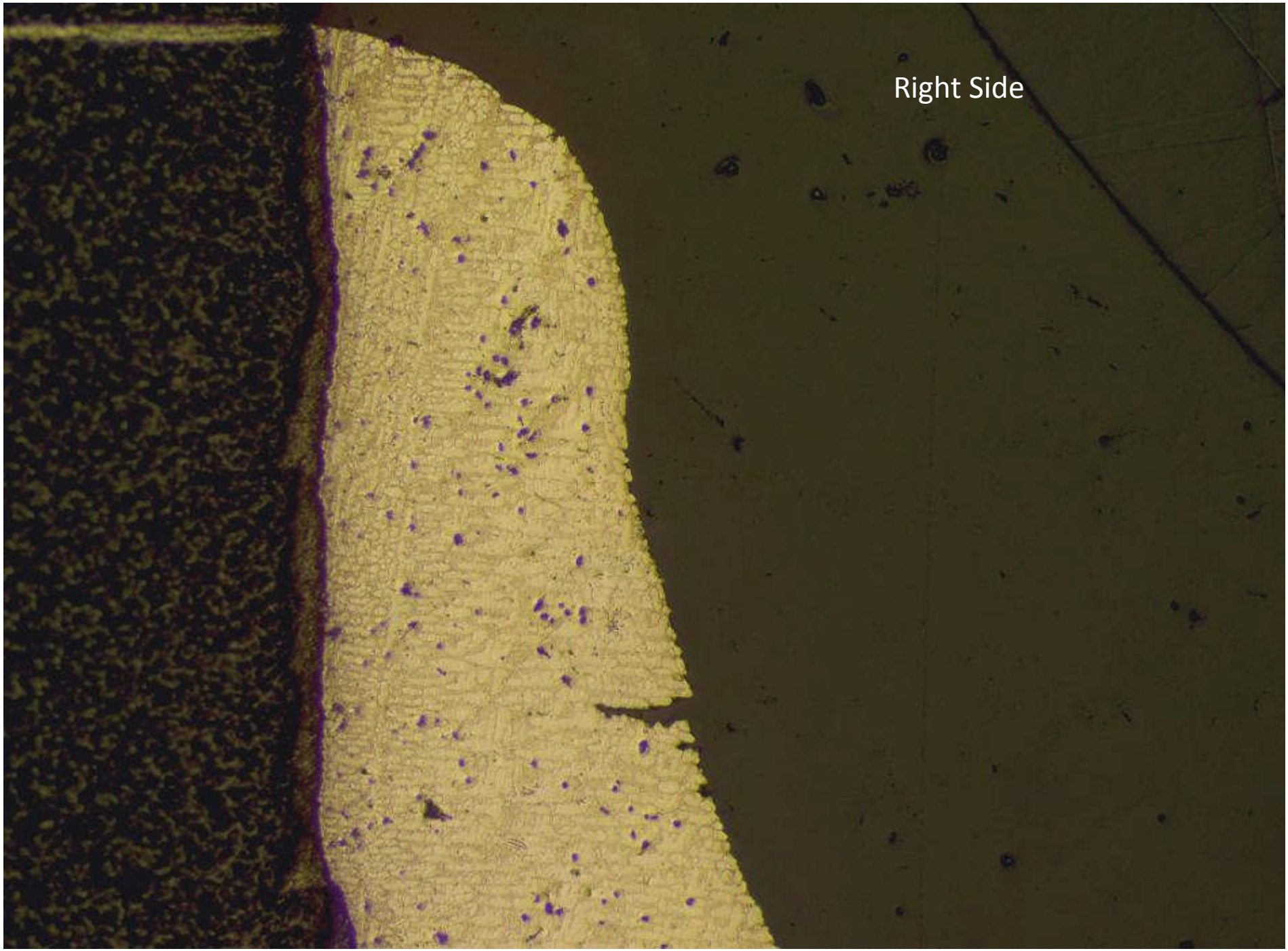


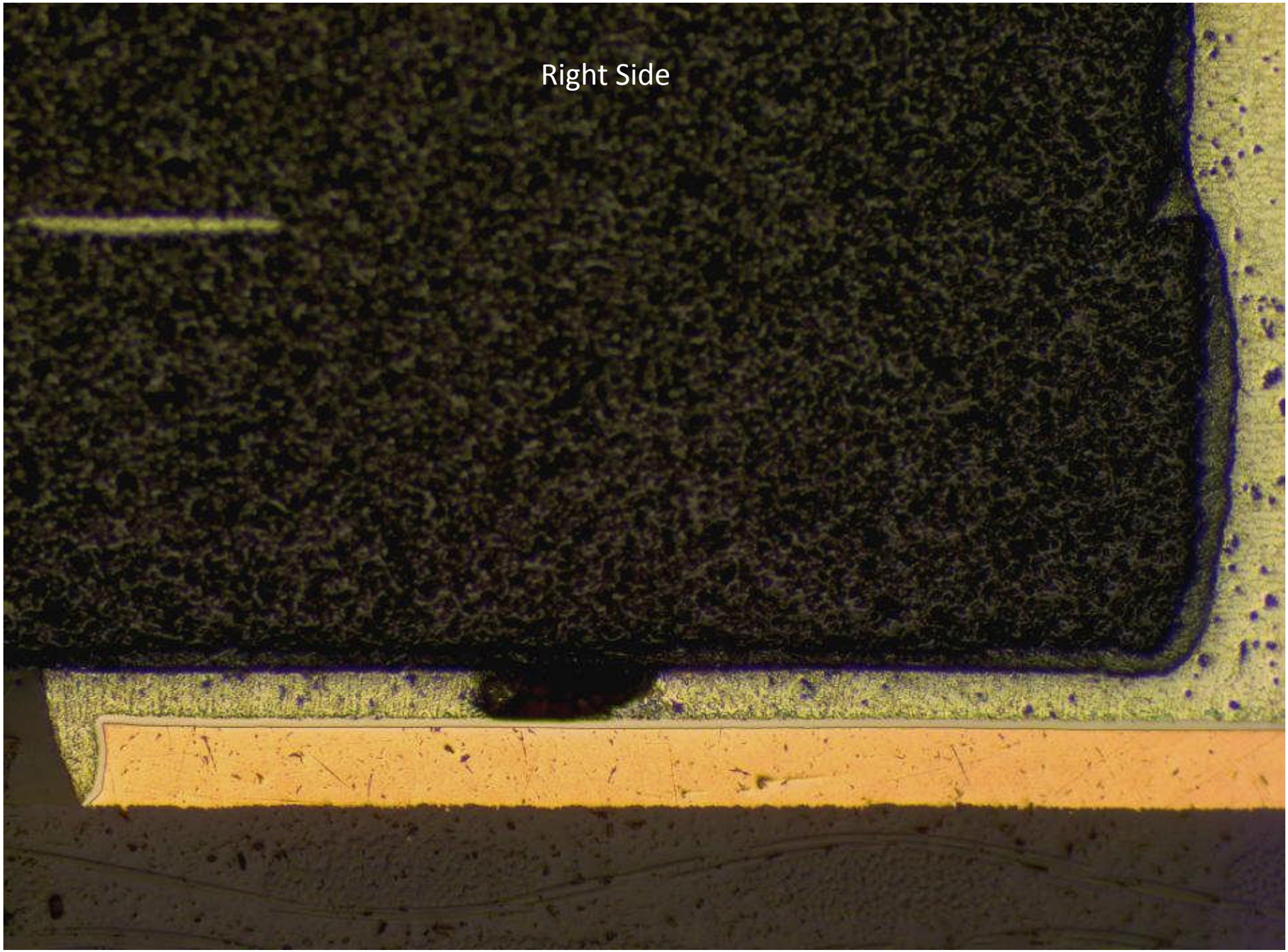

Left Side

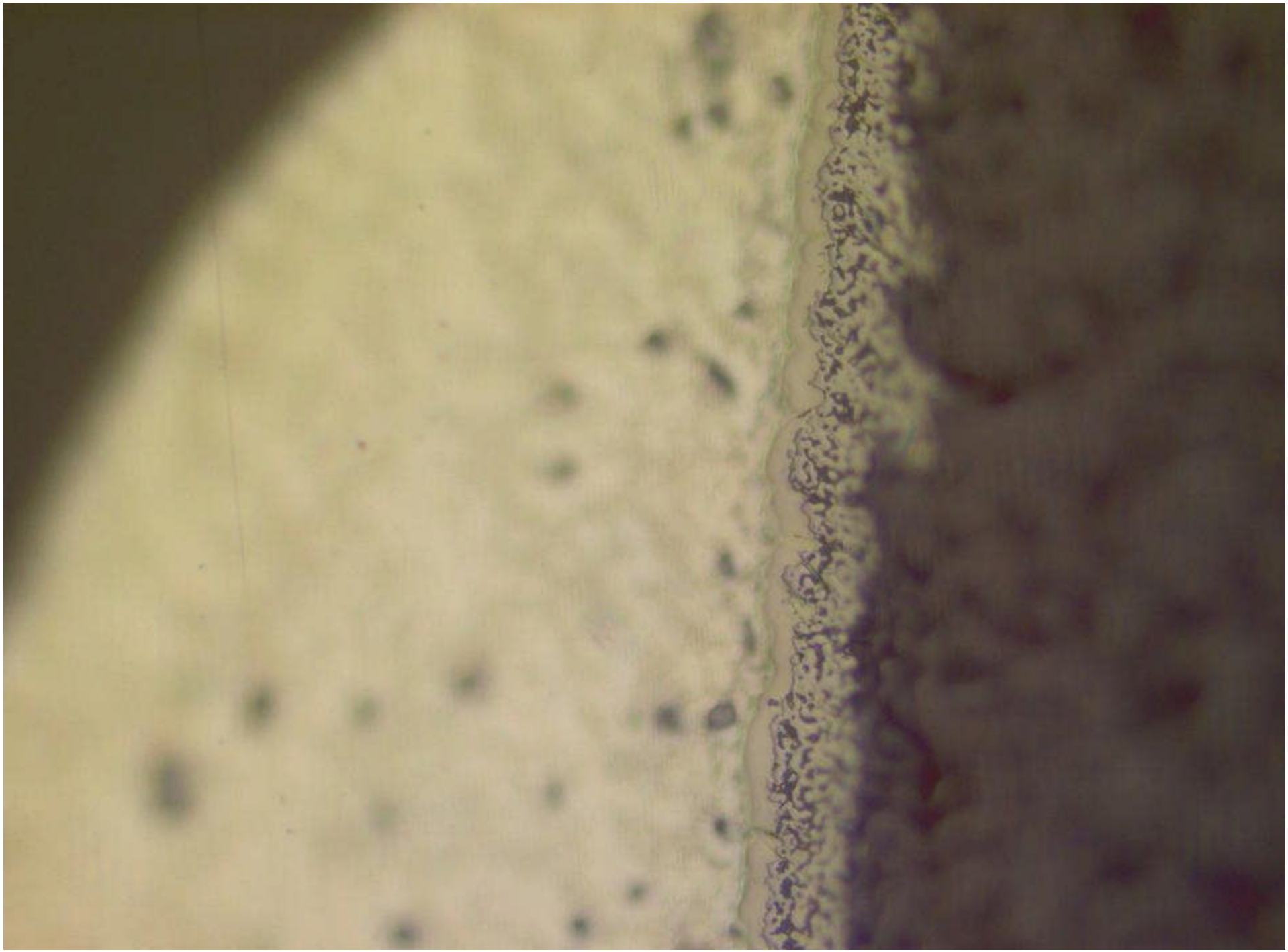

Left Side

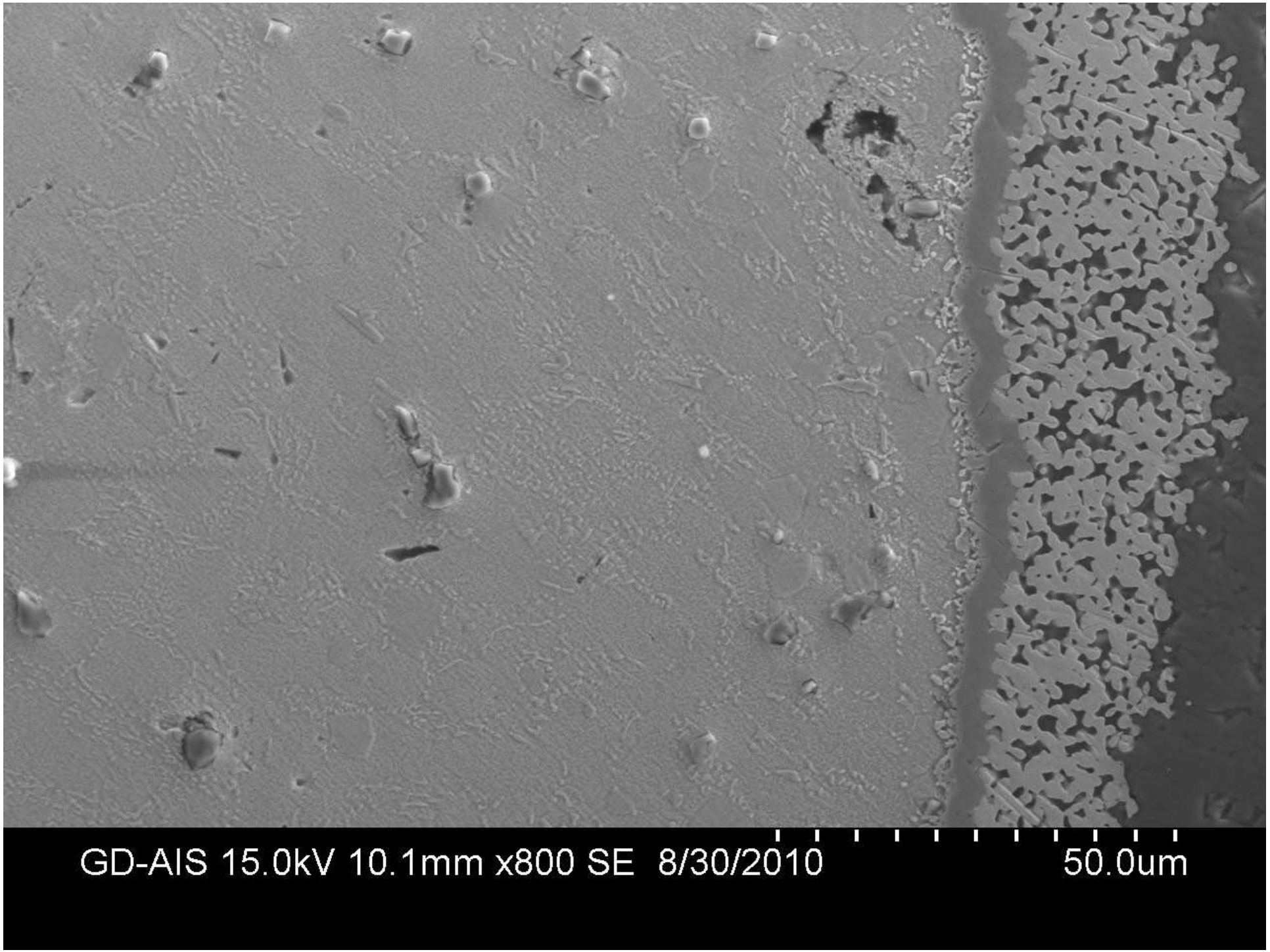
Left Side

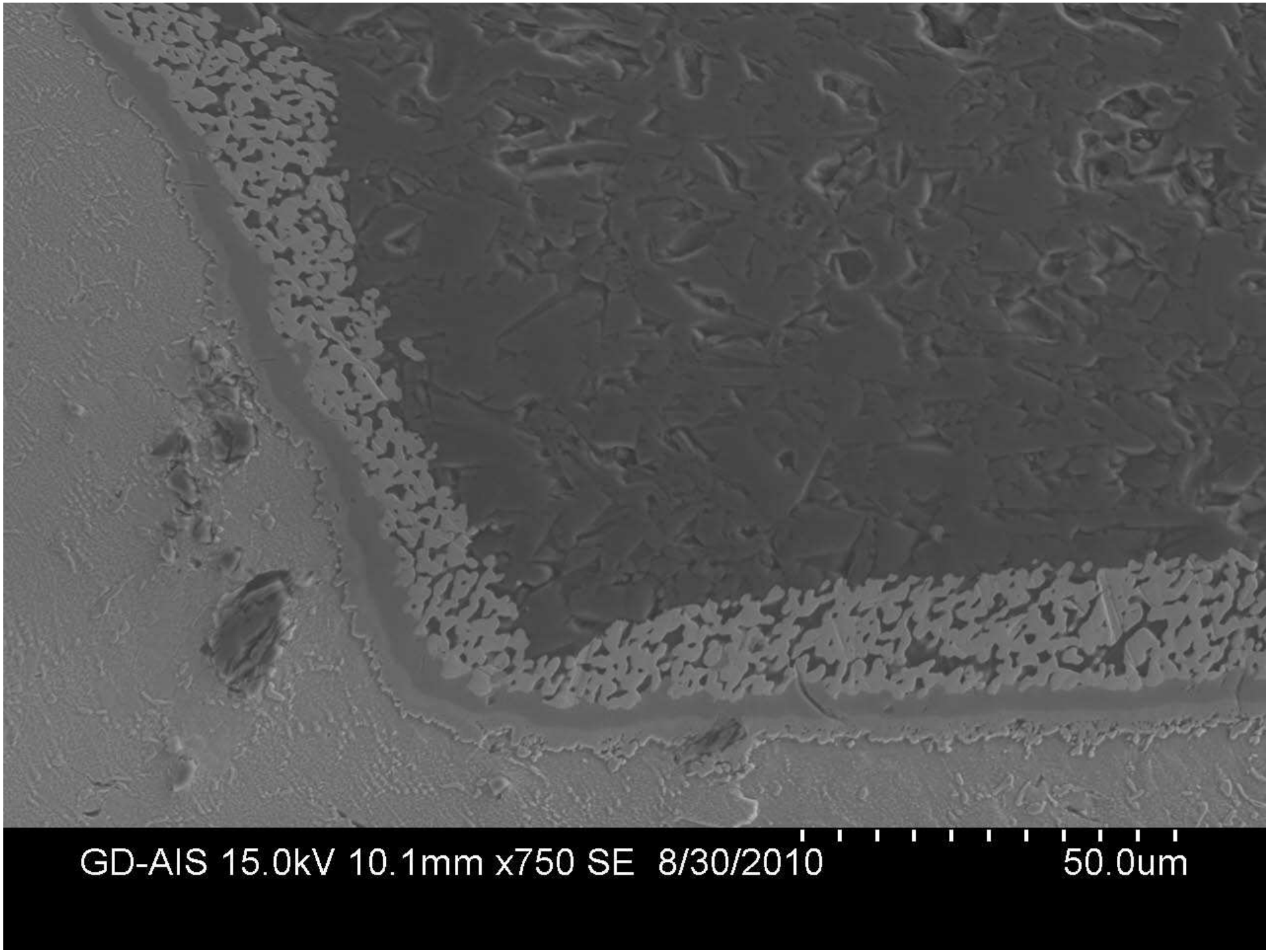

Right Side

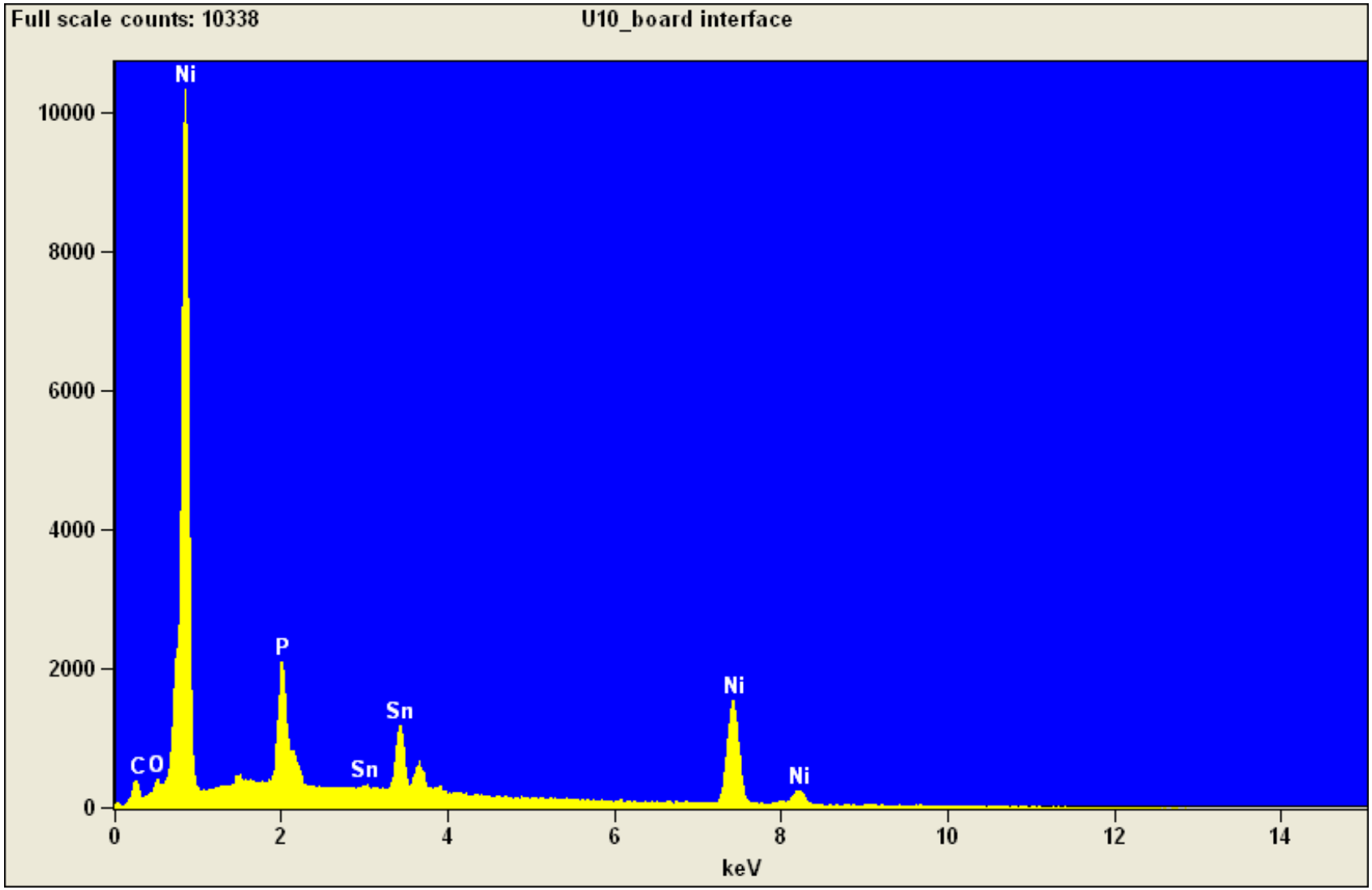

Right Side


Right Side



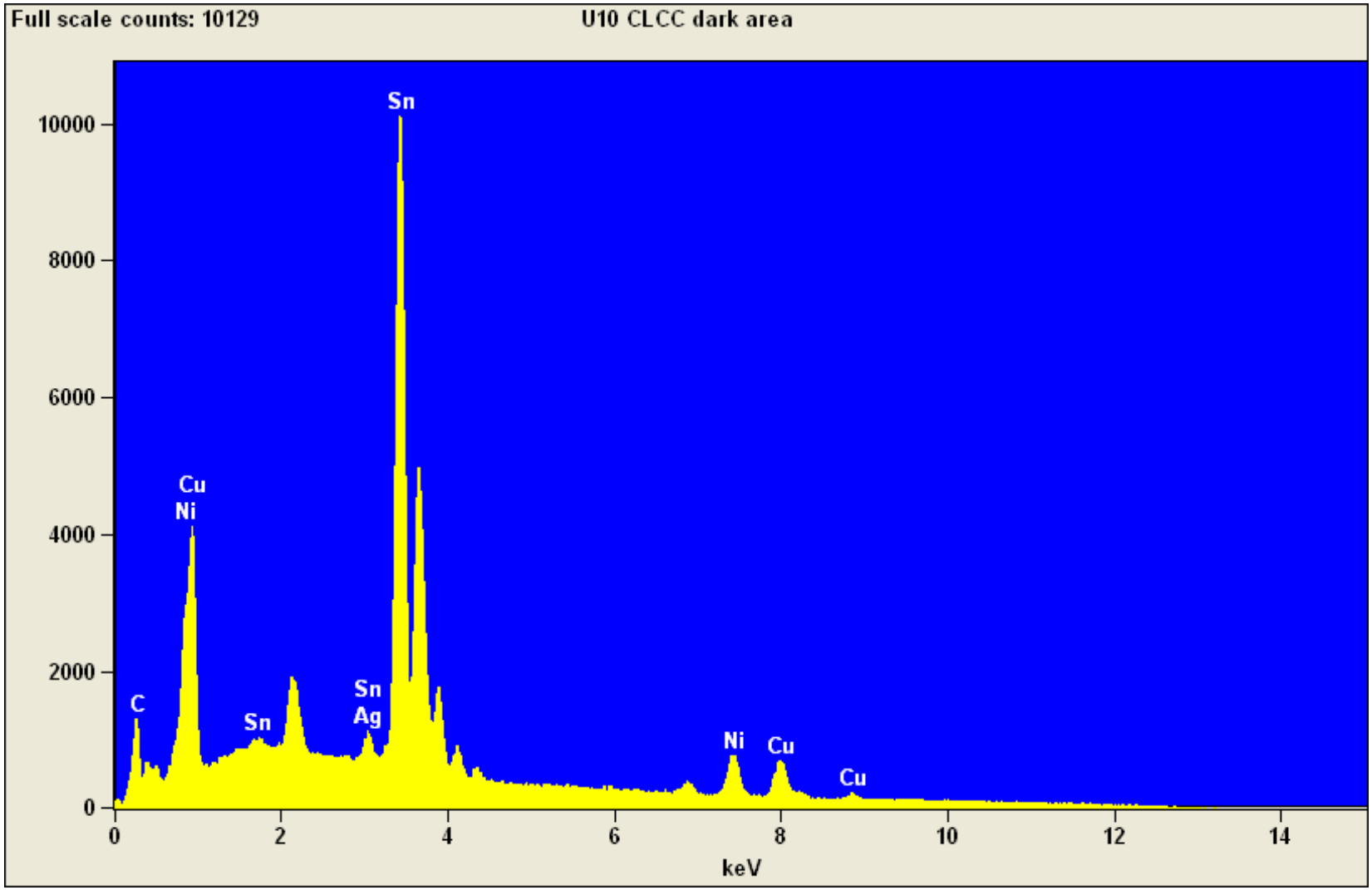

GD-AIS 15.0kV 10.1mm x800 SE 8/30/2010
50.0um


GD-AIS 15.0kV 10.1mm x750 SE 8/30/2010
50.0um



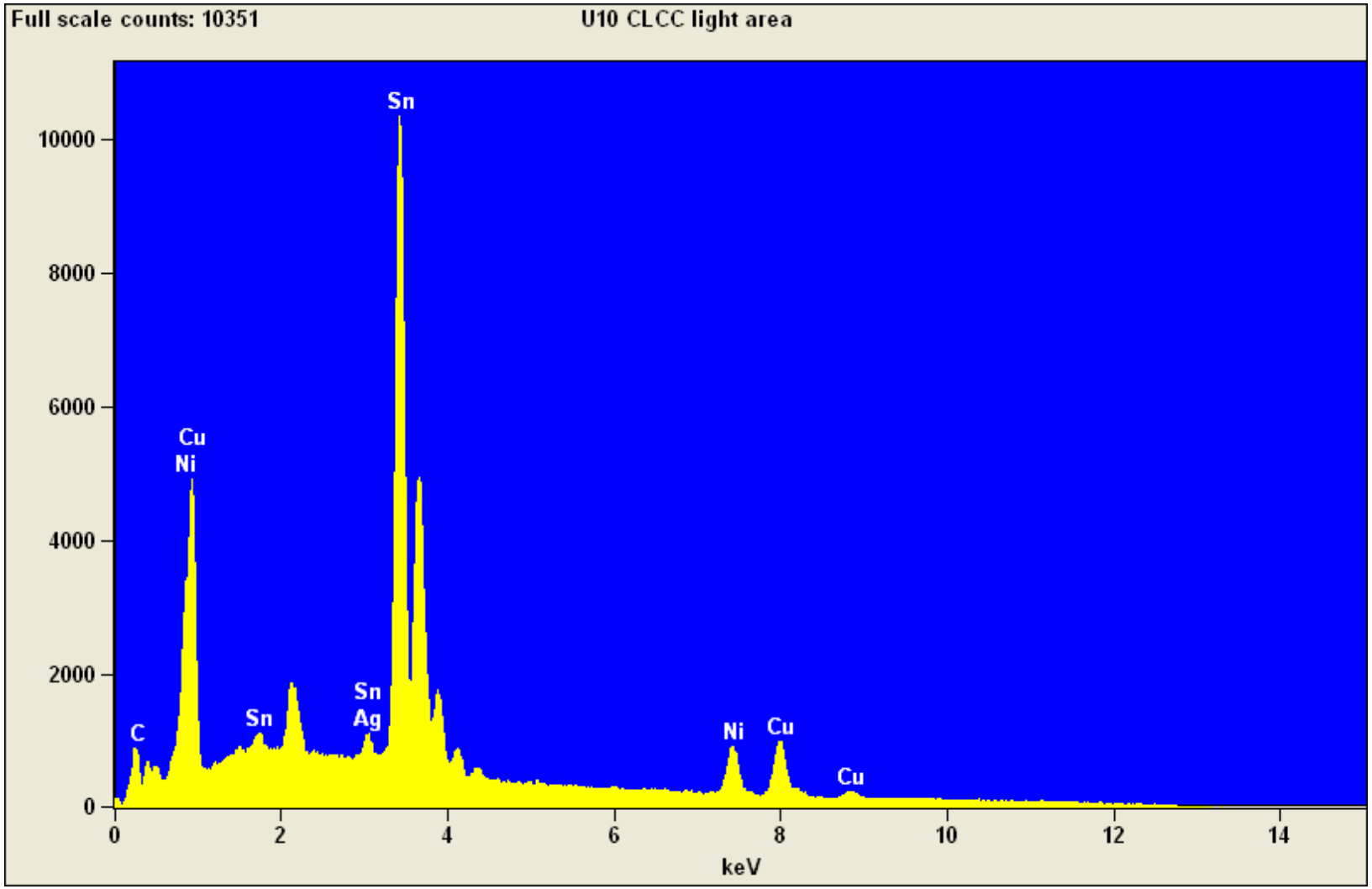
Quantitative Results for: U10_board interface

Element Line	Weight %	Atom %
P K	8.15	16.01
Ni K	70.43	73.01
Sn L	21.42	10.98
Total	100.00	100.00



Quantitative Results for: U10 CLCC dark area

Element Line	Weight %	Atom %
Ni K	10.53	17.47
Cu K	12.82	19.65
Ag L	0.00	0.00
Sn L	76.65	62.88
Total	100.00	100.00



Quantitative Results for: U10 CLCC light area

Element Line	Weight %	Atom %
Ni K	11.13	17.69
Cu K	18.15	26.67
Ag L	0.01	0.01
Sn L	70.71	55.62
Total	100.00	100.00